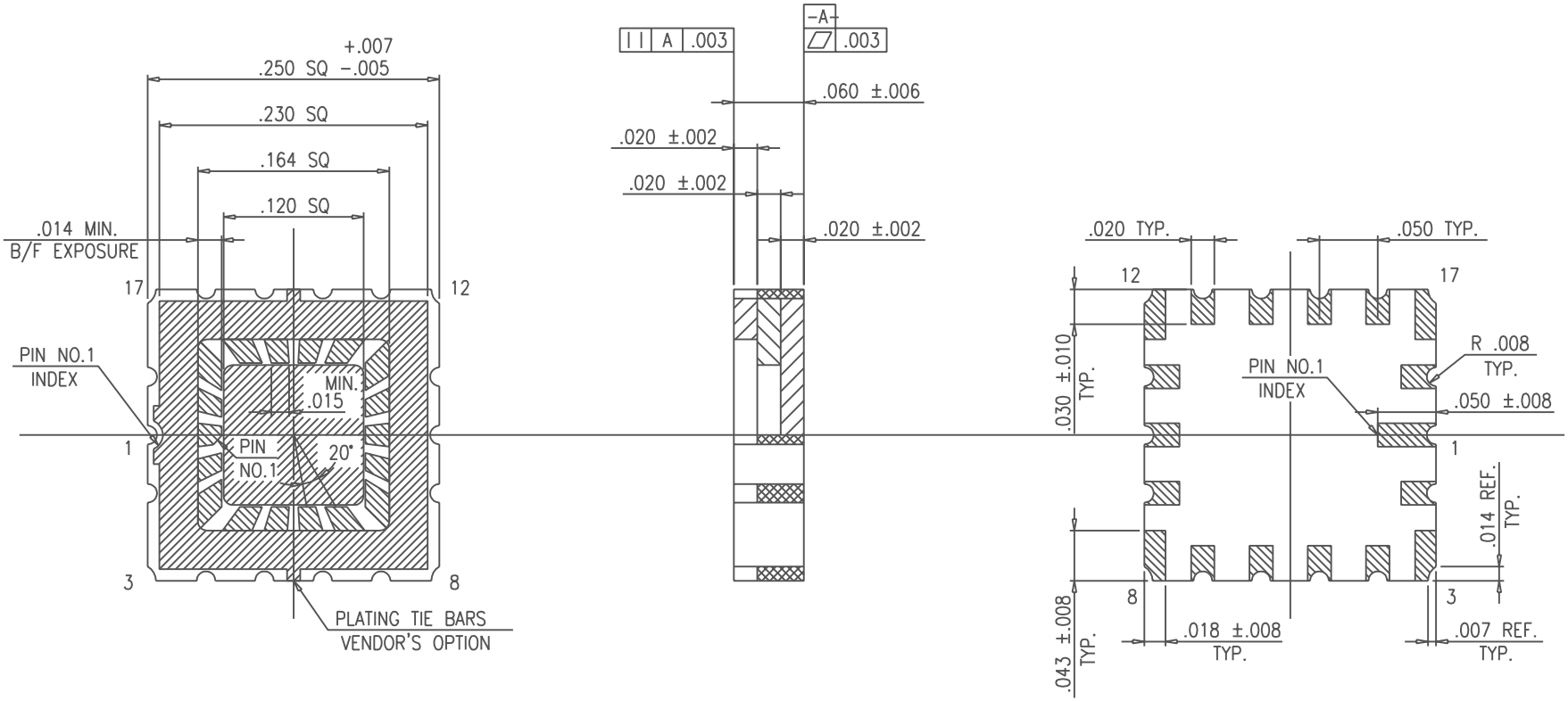
SSM P/N LCC01810



NOTES:

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PALTED 60 MICRO INCHES MIN. THK. OVER NICKEL PLATING. UNLESS OTHERWISED SPECIFIED IN PURCHASE ORDER.
2. FLATNESS PERTAINS TO METALLIZED PADS ONLY.
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.(ZERO GROUND)
4. LEAD TO LEAD LEAKAGE MUST NO EXCEED 1 NANO AMPS AT 100 V D.C.

S=0
D=0

CHANGED DWG NO. AND NAME

PAO-18C

MODIFICATIONS					
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 18 LCC (.164 SQ. CAV.)	TOLERANCES: UNLESS OTHERWISE SPECIFIED ± 1 % N.L.T ±.005 THIRD ANGLE PROJECTION	DRAWN M.M	CHECKED T.I / T.O
SCALE 10/1	MATERIAL KYOCERA A-473	APPROVED K.I / Y.S	DATE 5.10.'86
KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. PB-C86280	SHEET /

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
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